

Quarterly Reliability Monitoring Results

Quarters: Q1/2022 to Q4/2023

Based on structural similarity

	User Part Number PESD2USB3UXT-Q					
oratory	Part Description					
	NXP ICN8 Protection INDI					
ability labs	SMD package					
C-Q101 Test	Test Conditions	Duration	# Lots	# Quantity	# Rejects	
TEST						
Pre- and Post-Stress						
Electrical Test	Tamb = 25 °C	N/A	see below	all parts	see below	
PC Preconditioning	JESD22-A113 Bake Tamb = 125 °C Soak Tamb = 85 °C, RH = 85% Reflow soldering	24 hours 168 hours 3 cycles	524	22940	0	
1 reconditioning	<u>-</u>	5 6,6.65	324	22340	0	
HTRB High Temperature Reverse Bias	M1038 Method A	1000 hours	30	1280	0	
TC Temperature Cycling	JESD22-A104 -65 °C to Tjmax, not to exceed 150°C	1000 cycles	156	7080	0	
UHAST Unbiased HAST	JESD22-A118 Tamb = 130 °C, RH = 85 %	– 96 hours	156	7080	0	
AC Autoclave	JESD22-A102 Tamb = 121 °C, RH = 100 % Pressure = 205 kPa (29.7 psia)					
H3TRB High Humidity High Temperature Reverse Bias	JESD22-A101 Tamb = 85 °C, RH = 85%, VR = 80 % of rated reverse voltage $^{[1]}$	1000 hours	156	7080	0	
IOL Intermittent Operating Life	MIL-STD-750 Method 1037 ton = toff, devices powered to insure $\Delta Tj = 100$ °C for 15000 cycles	1000 hours	n.a.	n.a.	n.a.	
RSH Posictance to Solder Heat	JESD22-A111	10 -	56	1700	0	
	200 -C ± 3 -C	10 S	56	1/00	0	
SD Solderability	J-STD-002		56	1700	0	
1	bility labs C-Q101 Test TEST Pre- and Post-Stress Electrical Test PC Preconditioning HTRB High Temperature Reverse Bias TC Temperature Cycling UHAST Unbiased HAST AC Autoclave H3TRB High Humidity High Temperature Reverse Bias IOL Intermittent Operating Life RSH Resistance to Solder Heat SD	Part Description NXP ICN8 SMD package C-Q101 Test Test Conditions TEST Pre- and Post-Stress Electrical Test Tamb = 25 °C JESD22-A113 Bake Tamb = 125 °C Soak Tamb = 85 °C, RH = 85% Preconditioning MIL-STD-750-1 HTRB M1038 Method A High Temperature Reverse Bias Tj = Tjmax, Vr = 100% of max. datasheet reverse voltage TC JESD22-A104 Temperature Cycling JESD22-A104 -65 °C to Tjmax, not to exceed 150°C UHAST JESD22-A118 Unbiased HAST JESD22-A118 JESD22-A102 Tamb = 121 °C, RH = 85 % AC Tamb = 121 °C, RH = 100 % Autoclave Pressure = 205 kPa (29.7 psia) H3TRB JESD22-A101 Temperature Reverse Bias Tamb = 85 °C, RH = 85%, VR = 80 % of rated reverse voltage ^[1] IOL MIL-STD-750 Method 1037 ton = toff, devices powered to insure ΔTj = 100 °C for 15000 cycles RSH JESD22-A111 Jest cycles RSH JESD22-A111 Jest cycles RSH JESD22-A111 Jest cycles JESD22-	Part Description NXP ICN8 SMD package Protection INE	Part Description NXP ICN8 Protection INDI	Part Description NXP ICN8 SMD package SMD package	

^[1] The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

Calculation of FIT and MTTF

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

Wafer Fab	Technology	Quantity	Rejects	Failure Rate (FIT)	MTTF (hrs)
NXP ICN8	Protection INDI	1280	0	3,32	3,01E+08

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